



Material Content Data Sheet



Sales Product Name		BSC079N03LSC G		Issued		19. July 2018		
MA#		MA001269814						
Package		PG-TDSON-8-14		Weight*		122.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.709	0.58	0.58	5797	5797
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		80	
	non noble metal	zinc	7440-66-6	0.039	0.03		318	
	non noble metal	iron	7439-89-6	0.778	0.64		6363	
wire	non noble metal	copper	7440-50-8	31.590	25.84	26.52	258360	265121
	non noble metal	copper	7440-50-8	0.058	0.05	0.05	471	471
	encapsulation	organic material	carbon black	1333-86-4	0.260	0.21		2128
	plastics	epoxy resin	-	8.065	6.60		65958	
	inorganic material	silicondioxide	60676-86-0	43.705	35.74	42.55	357447	425533
leadfinish	non noble metal	tin	7440-31-5	1.243	1.02	1.02	10162	10162
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	306	306
solder	noble metal	silver	7440-22-4	0.026	0.02		213	
	non noble metal	tin	7440-31-5	0.021	0.02		171	
	non noble metal	lead	7439-92-1	0.996	0.81	0.85	8147	8531
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		44	
	non noble metal	zinc	7440-66-6	0.021	0.02		175	
	non noble metal	iron	7439-89-6	0.428	0.35		3497	
heat sink CLIP	non noble metal	copper	7440-50-8	17.360	14.20	14.57	141979	145695
	non noble metal	iron	7439-89-6	0.017	0.01		138	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		42	
	non noble metal	copper	7440-50-8	16.898	13.82	13.83	138204	138384
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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